



# PBSS4041PT

60 V, 2.7 A PNP low V<sub>CEsat</sub> transistor

20 September 2024

Product data sheet

## 1. General description

PNP low V<sub>CEsat</sub> transistor in a SOT23 small Surface-Mounted Device (SMD) plastic package.

NPN complement: PBSS4041NT

## 2. Features and benefits

- Very low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability I<sub>C</sub> and I<sub>CM</sub>
- High collector current gain (h<sub>FE</sub>) at high I<sub>C</sub>
- High energy efficiency due to less heat generation
- Smaller required Printed-Circuit Board (PCB) area than for conventional transistors
- AEC-Q101 qualified

## 3. Applications

- Loadswitch
- Battery-driven devices
- Power management
- Charging circuits
- Power switches (e.g. motors, fans)

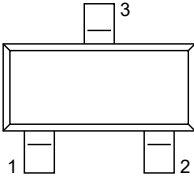
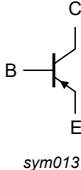
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	-60	V
I <sub>C</sub>	collector current		-	-	-2.7	A
I <sub>CM</sub>	peak collector current	single pulse; t <sub>p</sub> ≤ 1 ms	-	-	-8	A
R <sub>CEsat</sub>	collector-emitter saturation resistance	I <sub>C</sub> = -3 A; I <sub>B</sub> = -300 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	70	120	mΩ

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 SOT23	 sym013
2	E	emitter		
3	C	collector		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
<a href="#">PBSS4041PT</a>	SOT23	plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body	<a href="#">SOT23</a>

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
PBSS4041PT	%BL

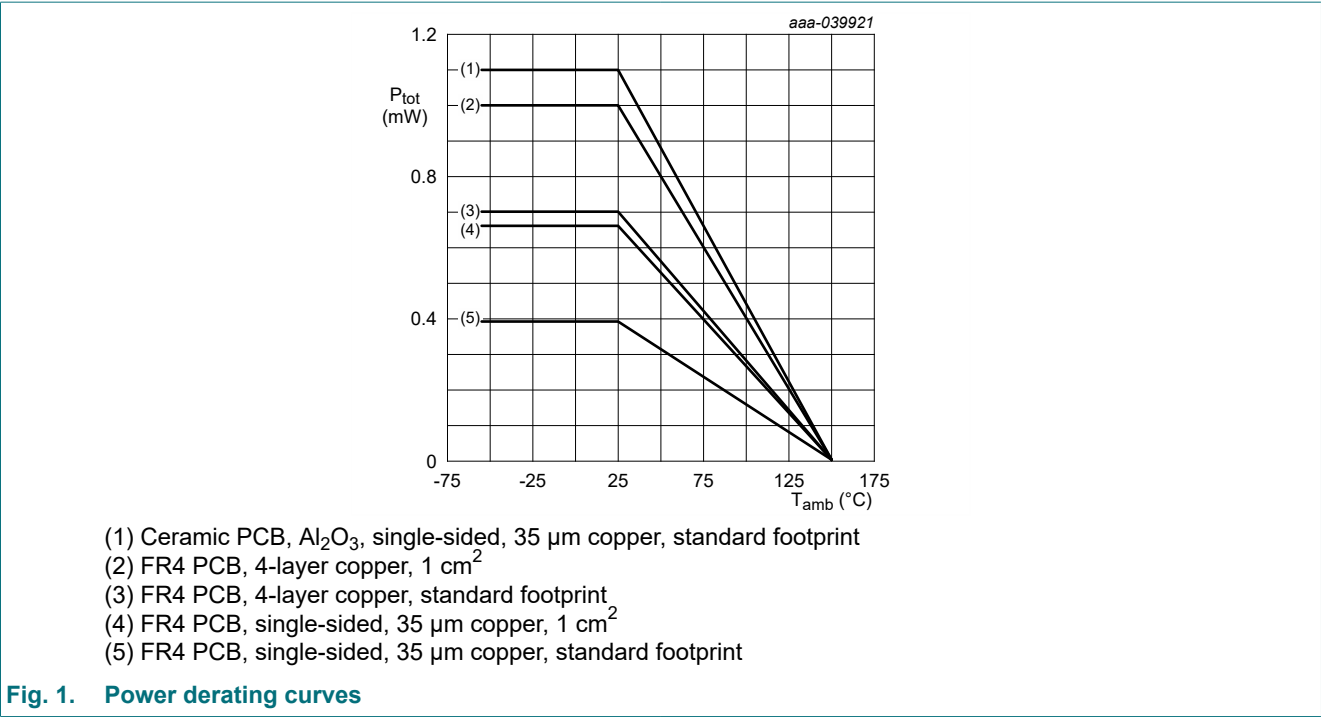
[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CBO</sub>	collector-base voltage	open emitter		-	-60	V
V <sub>CEO</sub>	collector-emitter voltage	open base		-	-60	V
V <sub>EBO</sub>	emitter-base voltage	open collector		-	-5	V
I <sub>C</sub>	collector current			-	-2.7	A
I <sub>CM</sub>	peak collector current	single pulse; t <sub>p</sub> ≤ 1 ms		-	-8	A
I <sub>B</sub>	base current			-	-1	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	0.39	W
			[2]	-	0.66	W
			[3]	-	0.7	W
			[4]	-	1	W
			[5]	-	1.1	W
T <sub>j</sub>	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided, 35 µm copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
- [3] Device mounted on an FR4 PCB, 4-layer, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, 4-layer, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
- [5] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, single-sided, 35 µm copper, tin-plated and standard footprint.



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	320	K/W
			[2]	-	-	190	K/W
			[3]	-	-	180	K/W
			[4]	-	-	125	K/W
			[5]	-	-	115	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	62	K/W

- [1] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.  
[3] Device mounted on an FR4 PCB, 4-layer, tin-plated and standard footprint.  
[4] Device mounted on an FR4 PCB, 4-layer, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.  
[5] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, single-sided, 35 µm copper, tin-plated and standard footprint.

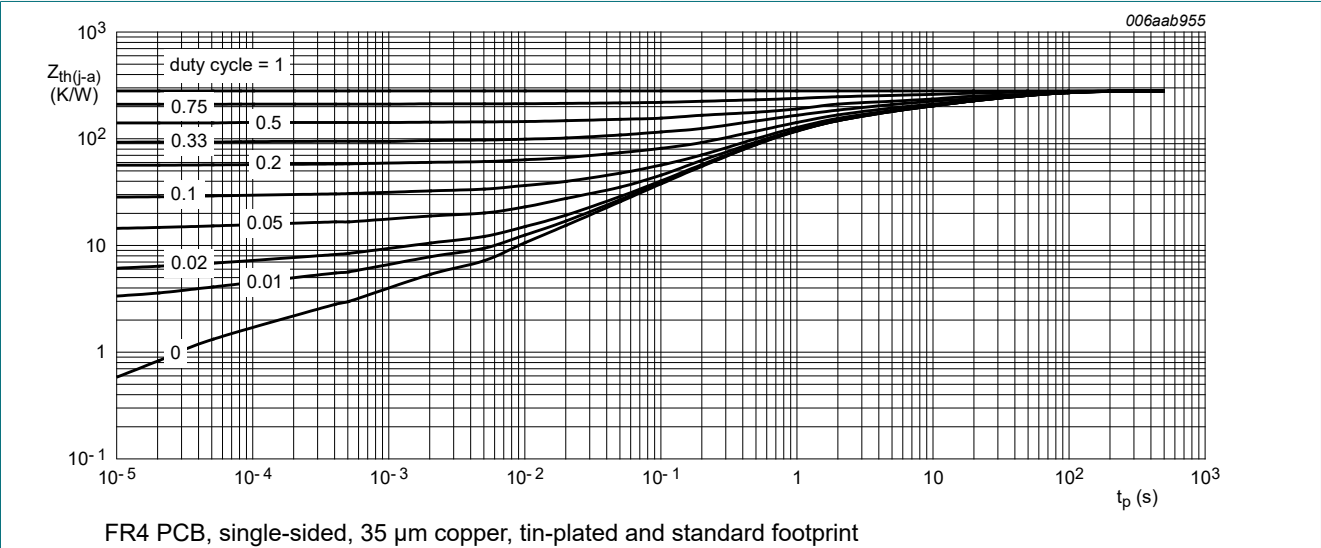


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

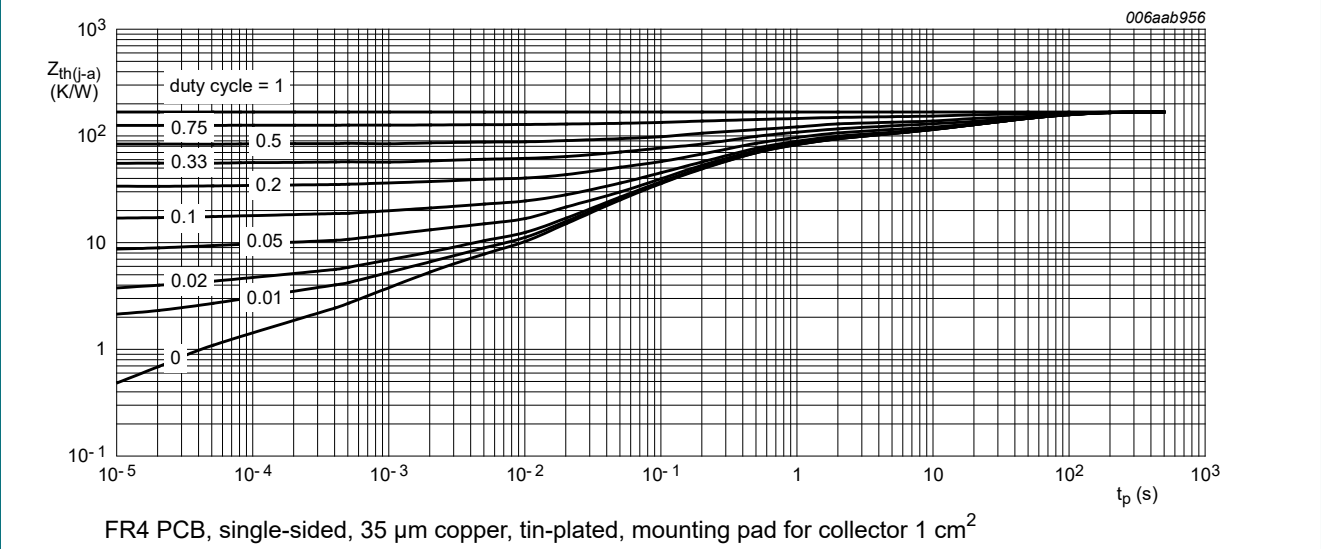
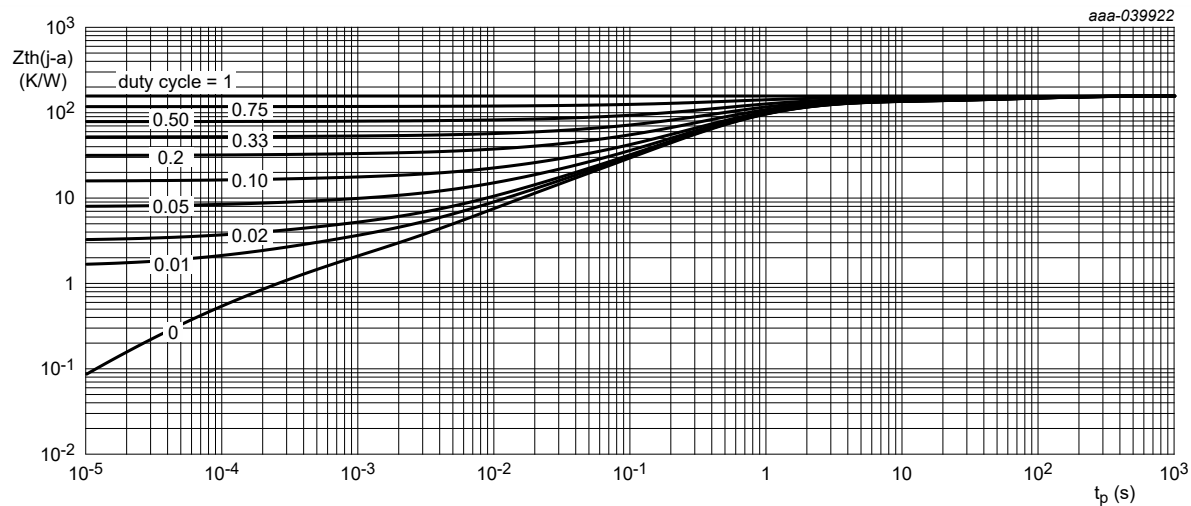
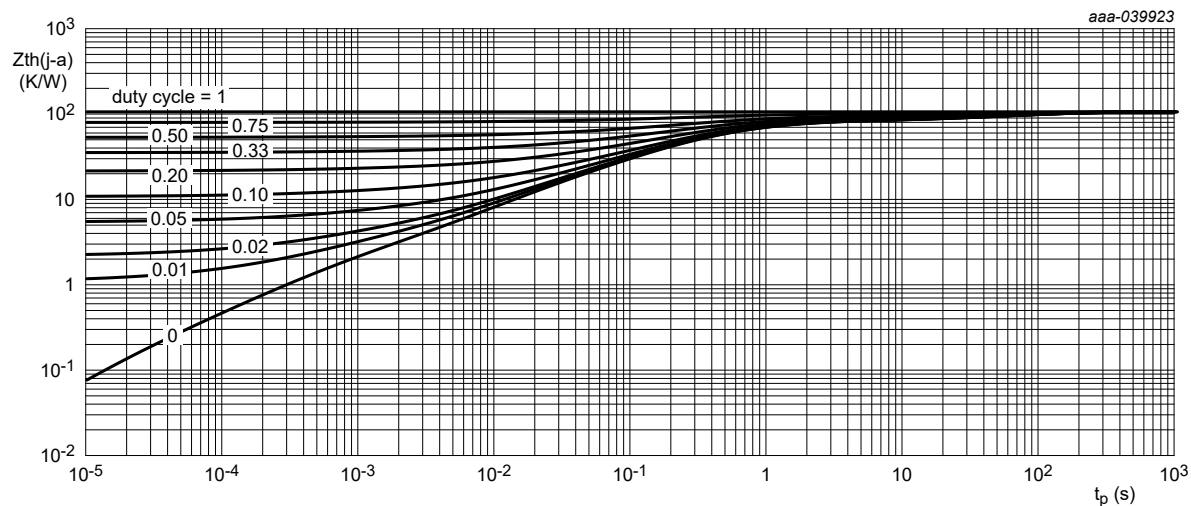


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



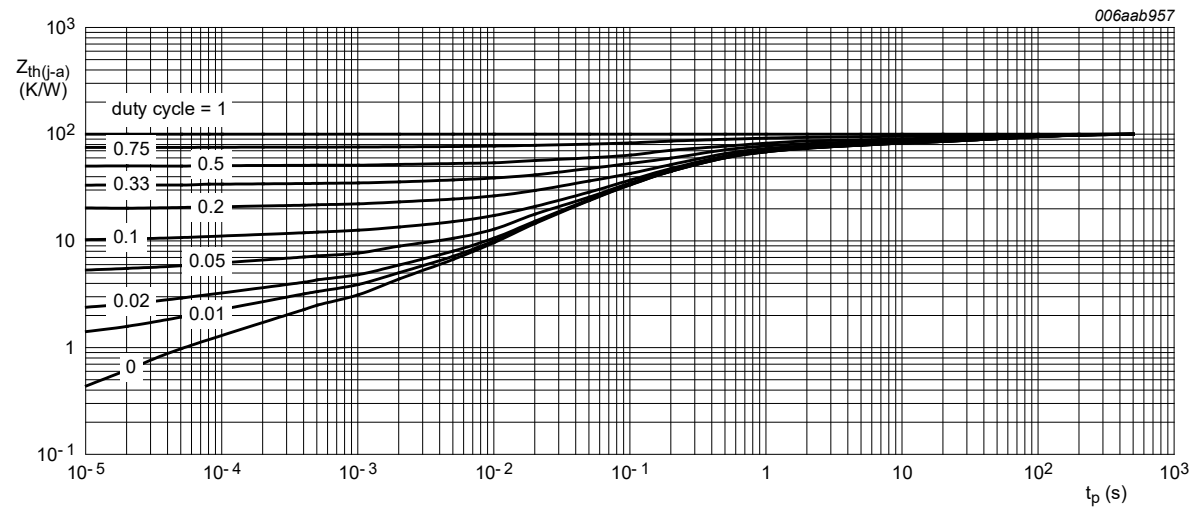
FR4 PCB, 4-layer, tin-plated and standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, 4-layer, tin-plated, mounting pad for collector 1 cm<sup>2</sup>

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, single-sided, 35 µm copper, tin-plated and standard footprint

Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = -100\text{ }\mu\text{A}$ ; $I_E = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-60	-	-	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	$I_C = -10\text{ mA}$ ; $I_B = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-60	-	-	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	$I_E = -100\text{ }\mu\text{A}$ ; $I_C = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-5	-	-	V
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -60\text{ V}$ ; $I_E = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-	-100	nA
		$V_{CB} = -60\text{ V}$ ; $I_E = 0\text{ A}$ ; $T_j = 150\text{ }^{\circ}\text{C}$		-	-	-55	$\mu\text{A}$
$I_{CES}$	collector-emitter cut-off current	$V_{CE} = -48\text{ V}$ ; $V_{BE} = 0\text{ V}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-	-100	nA
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}$ ; $I_C = 0\text{ A}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-	-100	nA
$h_{FE}$	DC current gain	$V_{CE} = -2\text{ V}$ ; $I_C = -500\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		200	300	-	
		$V_{CE} = -2\text{ V}$ ; $I_C = -1\text{ A}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		150	260	-	
		$V_{CE} = -2\text{ V}$ ; $I_C = -2\text{ A}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		120	210	-	
		$V_{CE} = -2\text{ V}$ ; $I_C = -4\text{ A}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		35	90	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -500\text{ mA}$ ; $I_B = -50\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-50	-75	mV
		$I_C = -1\text{ A}$ ; $I_B = -10\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-265	-390	mV
		$I_C = -1\text{ A}$ ; $I_B = -50\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-100	-150	mV
		$I_C = -2\text{ A}$ ; $I_B = -40\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-390	-600	mV
		$I_C = -3\text{ A}$ ; $I_B = -300\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-205	-360	mV
$R_{CEsat}$	collector-emitter saturation resistance			-	70	120	m $\Omega$
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -1\text{ A}$ ; $I_B = -100\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-0.85	-1	V
		$I_C = -3\text{ A}$ ; $I_B = -300\text{ mA}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	-0.97	-1.15	V
$V_{BE}$	base-emitter voltage	$V_{CE} = -2\text{ V}$ ; $I_C = -2\text{ A}$ ; pulsed; $t_p \leq 300\text{ }\mu\text{s}$ ; $\delta \leq 0.02$		-	-0.8	-0.9	V
$t_d$	delay time	$V_{CC} = -12.5\text{ V}$ ; $I_C = -1\text{ A}$ ; $I_{B(on)} = -50\text{ mA}$ ; $I_{B(off)} = 50\text{ mA}$ ; $T_{amb} = 25\text{ }^{\circ}\text{C}$		-	20	-	ns
$t_r$	rise time			-	45	-	ns
$t_{on}$	turn-on time			-	65	-	ns
$t_s$	storage time			-	345	-	ns
$t_f$	fall time			-	75	-	ns
$t_{off}$	turn-off time			-	420	-	ns
$f_T$	transition frequency			-	135	-	MHz

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = -10 V; I <sub>E</sub> = 0 A; i <sub>e</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	38	-	pF

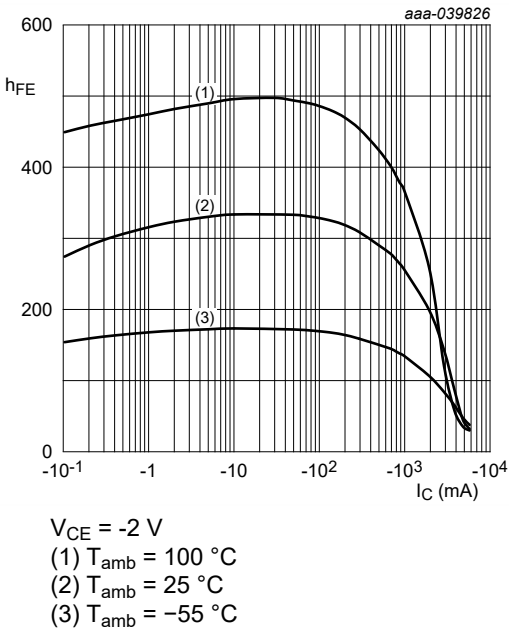


Fig. 7. DC current gain as a function of collector current; typical values

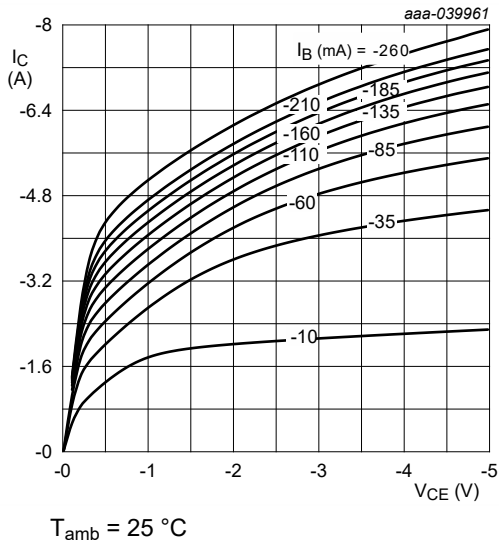


Fig. 8. Collector current as a function of collector-emitter voltage; typical values

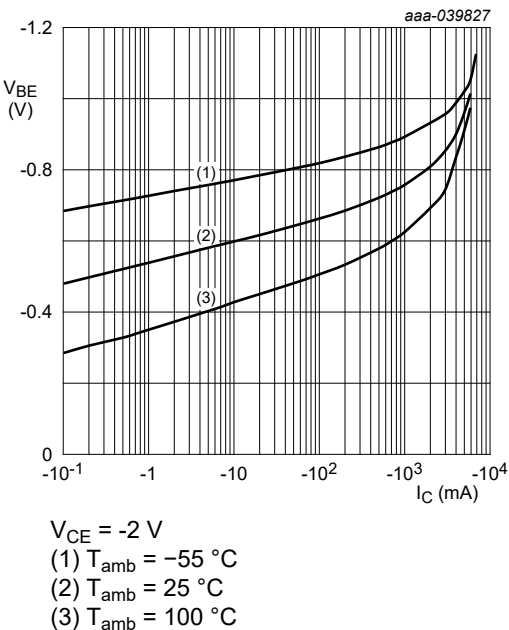


Fig. 9. Base-emitter voltage as a function of collector current; typical values

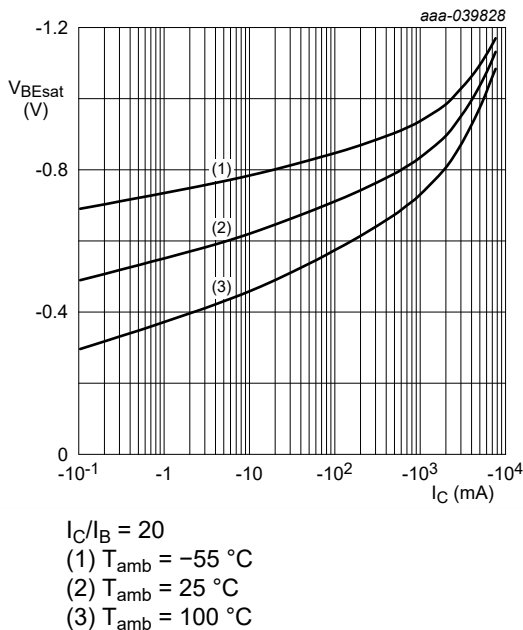


Fig. 10. Base-emitter saturation voltage as a function of collector current; typical values

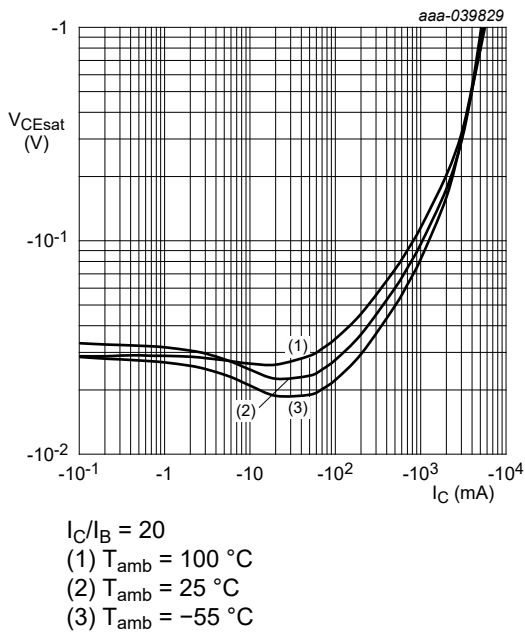


Fig. 11. Collector-emitter saturation voltage as a function of collector current; typical values

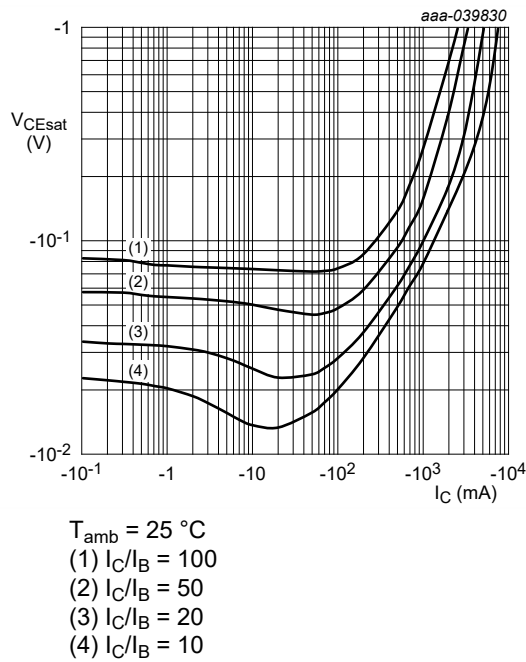


Fig. 12. Collector-emitter saturation voltage as a function of collector current; typical values

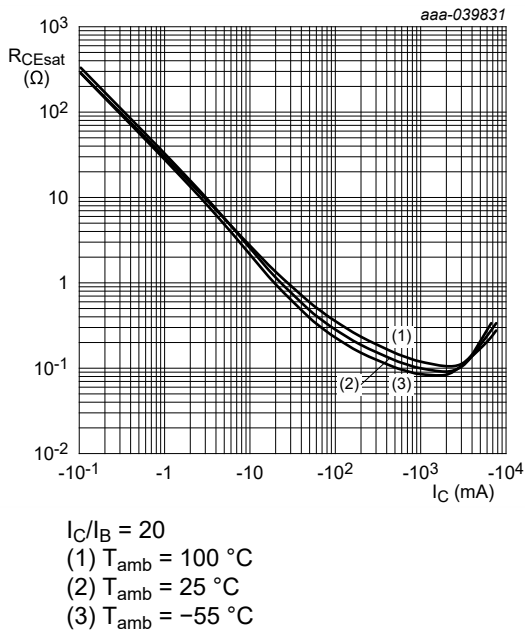


Fig. 13. Collector-emitter saturation resistance as a function of collector current; typical values

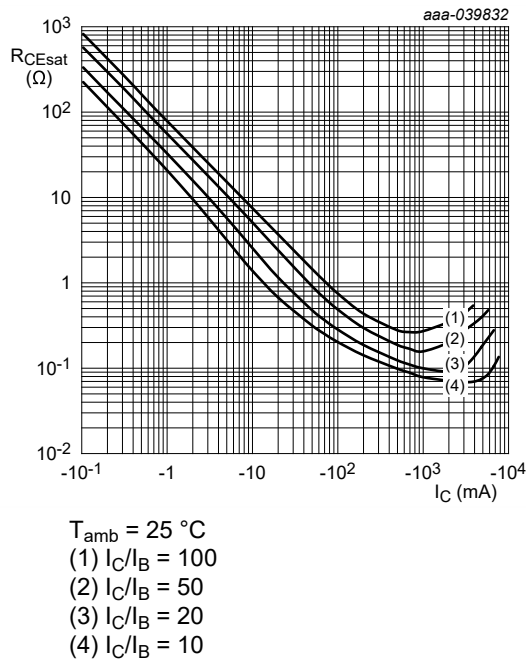


Fig. 14. Collector-emitter saturation resistance as a function of collector current; typical values



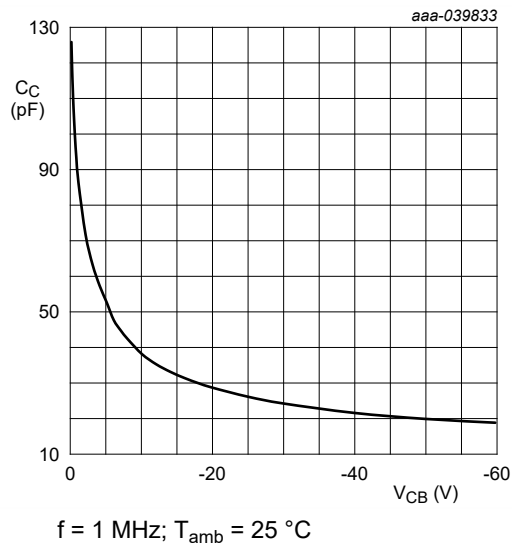


Fig. 15. Collector capacitance as a function of collector-base voltage; typical values

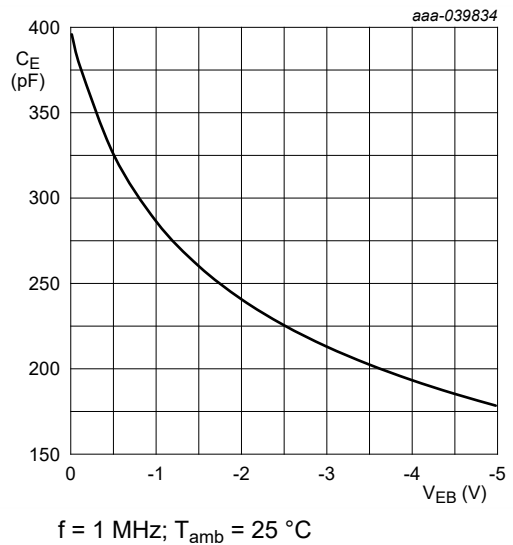


Fig. 16. Emitter capacitance as a function of emitter-base voltage; typical values

11. Test information

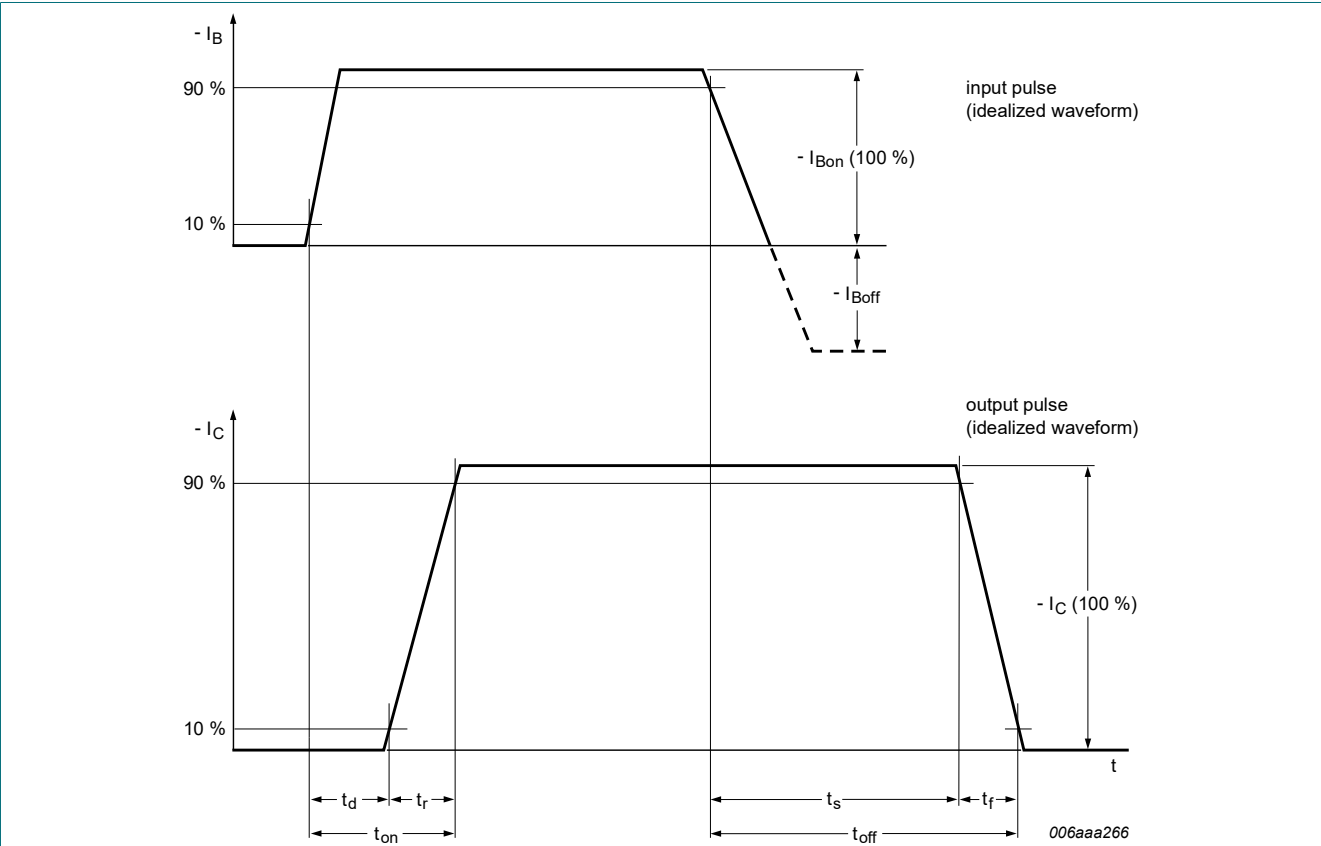


Fig. 17. Transistor switching time definition

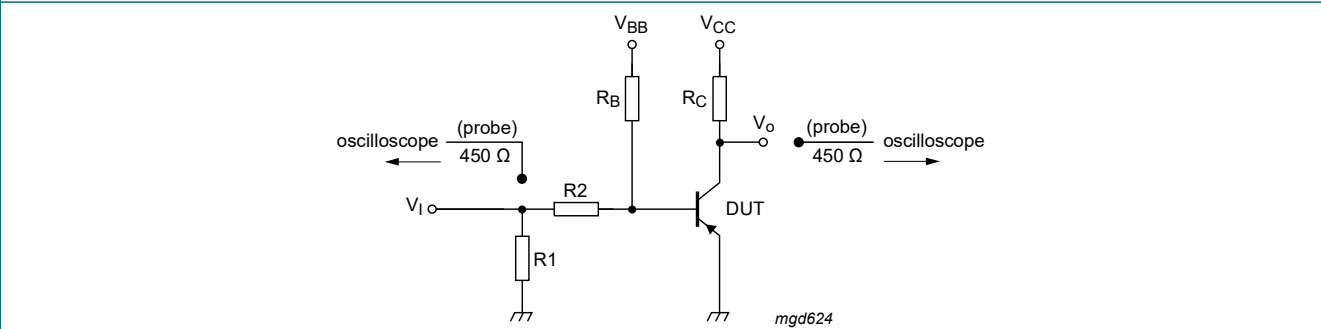
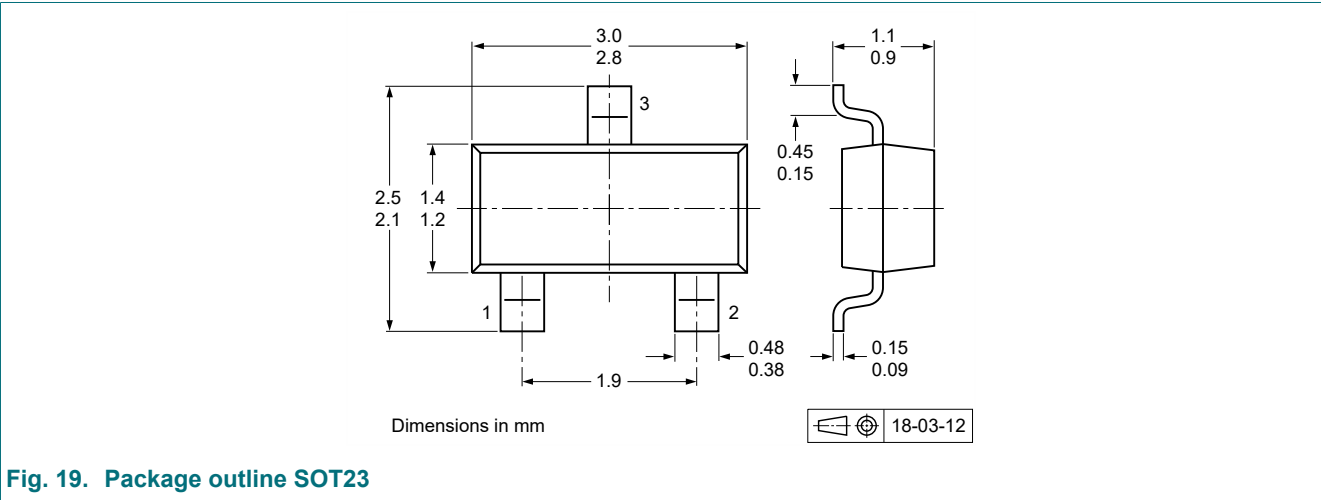


Fig. 18. Test circuit for switching times

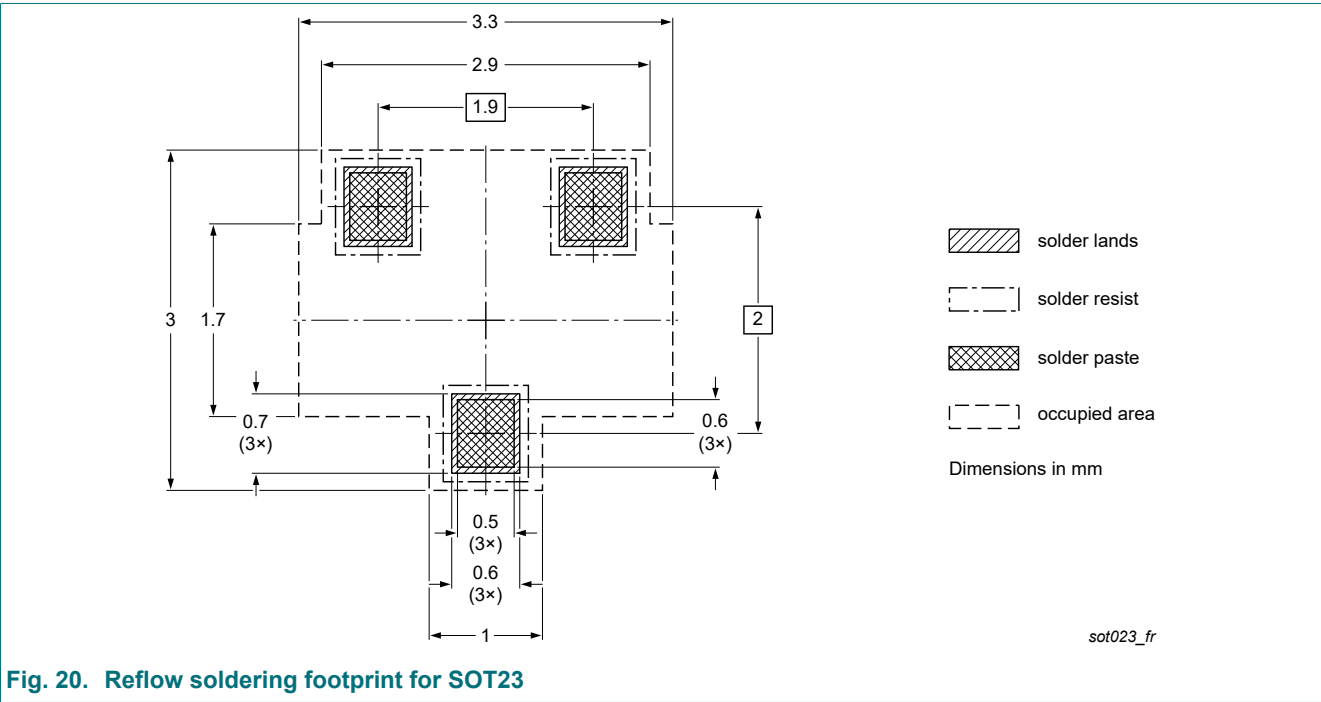
Quality information

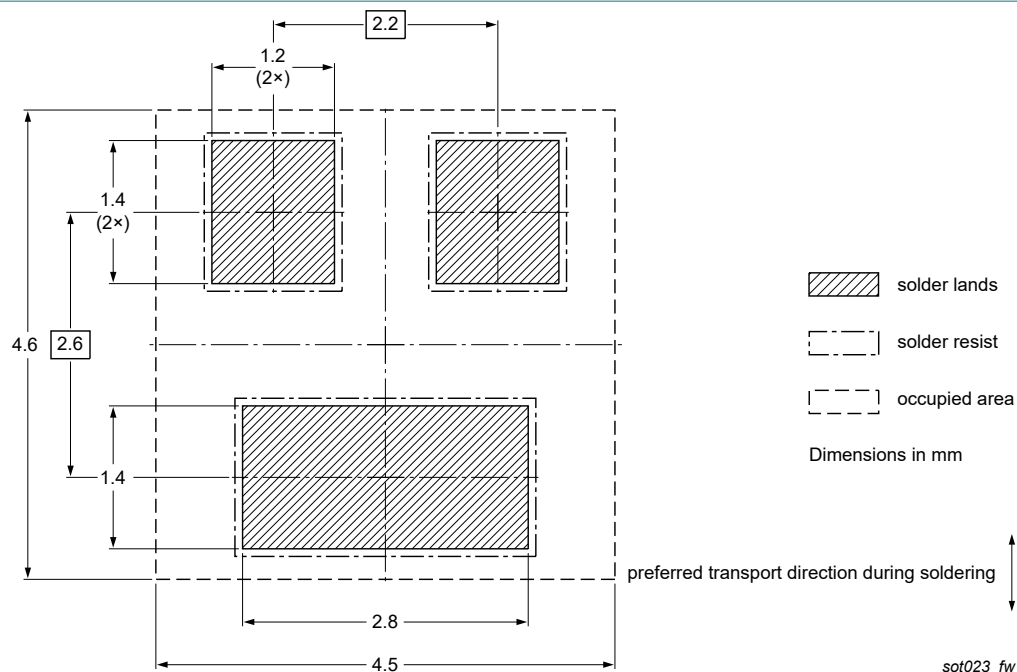
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline



13. Soldering





**Fig. 21. Wave soldering footprint for SOT23**

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBSS4041PT v.4	20240920	Product data sheet	-	PBSS4041PT v.3
Modifications:	• New graphics added, graphs updated and values changed.			
PBSS4041PT v.3	20230915	Product data sheet	-	PBSS4041PT_2
PBSS4041PT_2	20100131	Product data sheet	-	PBSS4041PT_1
PBSS4041PT_1	20100131	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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Date of release: 20 September 2024

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